



Press Release  
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**SMART Modular Technologies Expands Lineup of DDR3 High Density, Small Modules for Networking, Telecom, Storage, and Industrial Applications**

*SMART's new DDR3 ECC small modules target ATCA blade, MicroTCA, SBC, COM Express, and similar form-factor applications with commercial and industrial temperature options.*

NEWARK, Calif., January 12, 2010 - SMART Modular Technologies (WWH), Inc. ("SMART" or the "Company") (NASDAQ: SMOD), a leading independent manufacturer of memory modules and solid-state storage products, including SSDs, has expanded its lineup of DDR3 small modules. The new products include unbuffered and registered error-correction code (ECC) mini-DIMMs in very-low-profile (VLP) and standard heights as well as unbuffered and registered ECC SO-DIMMs. Serving a wide variety of applications in the networking, telecom, storage, and industrial markets, SMART's DDR3 ECC small modules are optimized for space savings, high density, lower power, and high performance.

Available in a broad range of configurations, SMART's DDR3 small modules are form-factor comparable to its DDR2 product line, allowing OEMs to continue using familiar memory modules while advancing performance and power savings with DDR3 technology. The DDR3 small modules handle commercial (0° to 70°C) and industrial (-40° to 85°C) temperature ranges.

"For small form-factor designs to exploit the benefits of memory technologies initially developed for computer servers and PCs, module manufacturers must apply a significant amount of engineering expertise to optimize and qualify these modules for operation in a wide range of alternative CPUs/platforms," said Mike Rubino, SMART's Vice President of Engineering. "SMART's design teams have done just that, and I am very pleased with our broad offering of tailored, small form-factor DDR3 modules that have already been qualified by a number of OEMs across a variety of application-specific processors."

The use of vertically mounted VLP mini-DIMMs is also becoming more common in space-constrained designs. "There is an ongoing need for higher-density memory in networking, telecom, and storage blade applications, and DDR3 memory with a small footprint is uniquely qualified to enable these next-generation designs," said Sam Caldwell from Semico Research Corp. "We expect products using DDR3 memory modules to begin launching in 2010, and the projected market for DDR3 technology in networking, telecom, and storage blade applications is expected to be \$1.32 billion for 2010."

Volume production of SMART's DDR3 small modules is expected to begin in Q1 2010. Details of the expanded lineup of DDR3 modules are included in the table below.

Module Type	Density	Size
SO-UDIMM (unbuffered w/ ECC)	1GB - 4GB	30mm
SO-RDIMM (registered)	2GB - 4GB	30mm
VLP Mini-UDIMM (unbuffered w/ ECC)	1GB - 4GB	18.8mm
Mini-UDIMM (unbuffered with ECC)	1GB - 4GB	30mm
VLP Mini-RDIMM (registered)	1GB - 4GB	18.8mm
Mini-RDIMM (registered)	1GB - 8GB	30mm

### About SMART

SMART is a leading independent designer, manufacturer and supplier of electronic subsystems to original equipment manufacturers, or OEMs. SMART offers more than 500 standard and custom products to OEMs engaged in the computer, industrial, networking, aerospace, defense and telecommunications markets. Taking innovations from the design stage through manufacturing and delivery, SMART has developed a comprehensive memory product line that includes DRAM, SRAM, and Flash memory in various form factors. SMART also offers high performance, high capacity SSDs for enterprise, defense, aerospace, industrial automation, medical, and transportation markets. SMART's presence in the U.S., Europe, Asia, and Latin America enables it to provide its customers with proven expertise in international logistics, asset management, and supply-chain management worldwide. See [www.smartm.com](http://www.smartm.com) for more information.

### Forward-Looking Statements

Statements contained in this press release, that are not statements of historical fact, including any statements that use the words "will," "believes," "anticipates," "project," "estimates," "expects," "intends" or similar words that describe the Company's or its management's future plans, objectives, or goals, are "forward-looking statements" and are made pursuant to the safe-harbor provisions of the Private Securities Litigation Reform Act of 1995. These forward-looking statements include those related to the Company's business strategies and product plans, the demand for higher-density memory and other features in various applications, the timing of product launches using DDR3 memory modules and the availability of DDR3 memory modules in production volumes, the size of the market for DDR3 technology in certain applications in 2010, and the market for the Company's products.

Such forward-looking statements involve known and unknown risks, uncertainties and other factors that could cause the actual results of the Company to be materially different from the historical results and/or from any future results or outcomes expressed or implied by such forward-looking statements. Factors that would cause or contribute to such differences include, but are not limited to, design, production or manufacturing difficulties, competitive factors, failure to meet protocols or MIL qualification, new products and technological changes, fluctuations in product prices as well as raw material costs and availability, dependence upon third-party vendors (including the performance of their products supplied to the Company), customer

demand, changes in industry standards or release plans, intellectual property disputes and other risks detailed in the Company's periodic report filings with the Securities and Exchange Commission, including the Company's Annual Report on Form 10-K for the fiscal year ended August 28, 2009 and recently filed Quarterly Report on Form 10-Q for the fiscal quarter ended November 27, 2009. Such risk factors as outlined in our periodic report filings and may not constitute all factors that could cause actual results to differ materially from those discussed in any forward-looking statement.

The Company operates in a continually changing business environment and new factors emerge from time to time. The Company cannot predict such factors, nor can it assess the impact, if any, from such factors on the Company or its results. Accordingly, our future results may differ materially from projections and investors are cautioned not to place undue reliance on any forward-looking statements. Forward-looking statements should not be relied upon as a prediction of actual results. These forward-looking statements are made as of today, and the Company does not currently intend, and has no obligation, to revise or update any forward-looking statements in order to reflect events or circumstances that may arise after the date of this press release.

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